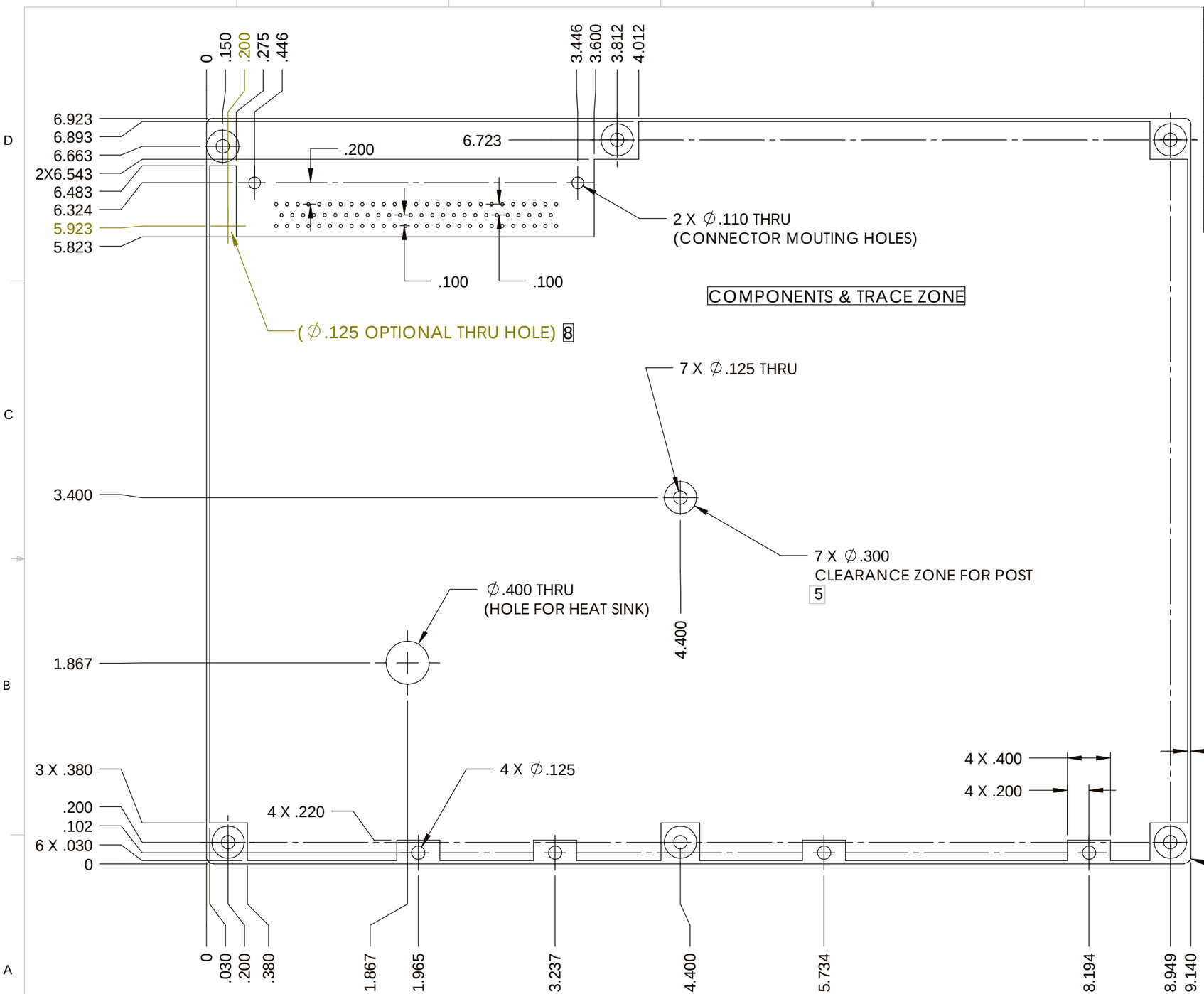
REVISIONS		
REV.	DESCRIPTION	DATE
A	BASELINE RELEASE	8/14/2008
B	ADDED HOLES FOR J105 CONNECTOR TO PCB; ADDED HEAT SINK HOLE, CHANGED PCB THICKNESS TO .093", INCREASED MAX COMPONENT HEIGHT TO 1.00"	8/18/2008
C	CHANGED HOLE LOCATIONS; INCREASED OVERALL BOARD SIZE	8/22/2008
D	REMOVED BOARD MOUNTED CONNECTOR (IS NOW MOUNTED TO FRT PNL); ADDED 2 X HOLES FOR ATTACHED PCB TO LVPS FRAME; CHANGED DESIGN OF VENTS	12/3/2008
E	ADDED 4X NEW HOLES NEAR FRT PNL AND KEEP OUT ZONES	4/17/2009
F	IN UPPER LEFT HAND, REMOVED ONE HOLE; EXTENDED COMPONENT/TRACE AREA ALONG CONNECTOR SIDE; CALLOUT 7 X THRU HOLE (WAS) 8 X THRU HOLE	6/1/2009
G	ADDED SHEET 3	6/3/2009
H	MOVED HEAT SINK HOLE PER BOARD LAYOUT CHANGES; ADDED OPTIONAL HOLE; ADDED G/N 8	7/1/2009
J	MOVED HEAT SINK HOLE LOCATION TO REFLECT NEW LOCATION AS SHOWN ON LATEST LAYOUT	4/13/2010



PCB DETAILS

LOOKING DOWN AT TOP OF PCB
(COMPONENTS SIDE)
SCALE: 1/1
PCB THICKNESS: .093

GENERAL NOTES: UNLESS OTHERWISE SPECIFIED

1. THIS INTERFACE CONTROL DOCUMENT CONTROLS THE THE INTERFACE OF COMPLETED LVPS BOARD AND IDPU CHASSIS
2. COMPONENT ENVELOPE DEFINES MAXIMUM ENVELOPE FOR ALL COMPONENTS
3. COMPONENT (TOP) SIDE OF BOARD TO HAVE EMI SHIELDING OVER CIRCUITRY; SHIELD TO ATTACH DIRECTLY TO BOARD VIA POSTS
4. FRONT PANEL CONNECTORS TYPE AND LOCATION AS SHOWN. ALL CONNECTORS SHALL BE FRONT MOUNTED.
5. PAD IS PLATED ON BOTH SIDES OF BOARD
6. SEE DOCUMENT RBSP_EFW_BPL_001 FOR ELECTRICAL INTERFACE.
7. SEE DOCUMENT RBSP_EFW_SYS_008 FOR CONNECTOR CABLING INFO.
8. OPTIONAL HOLE IS REMNANT OF EARLIER REVISION, HOLE IS NOT REQUIRED (SERVES NO PURPOSE)

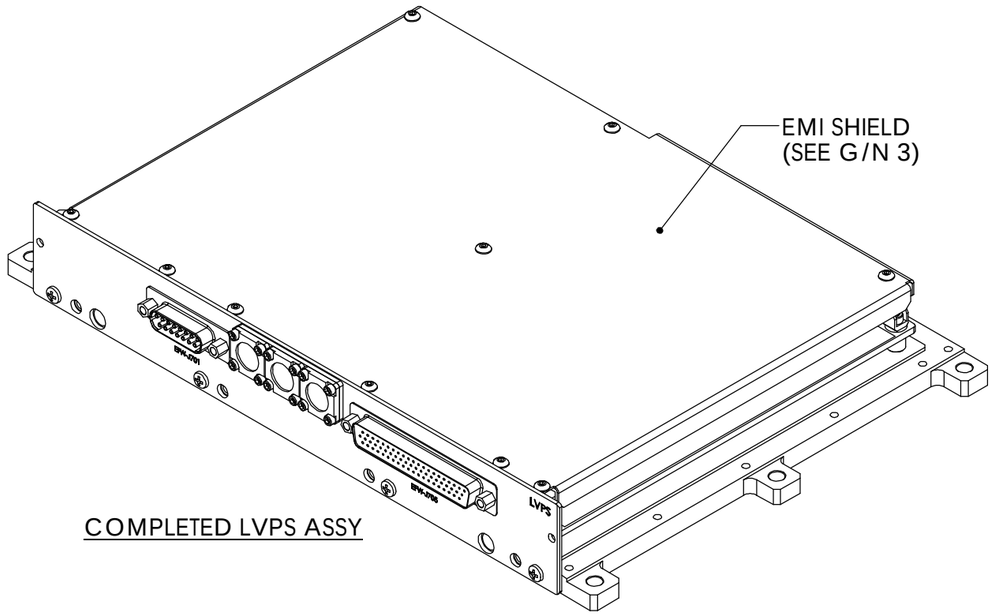
DRAWN	DONAKOWSKI
DATE	14 AUG 2008

DIMENSIONS ARE IN INCHES
TOLERANCES:
FRACTIONAL ±
ANGULAR: MACH ±.5° BEND ±2°
TWO PLACE DECIMAL ±.030
THREE PLACE DECIMAL ±.005

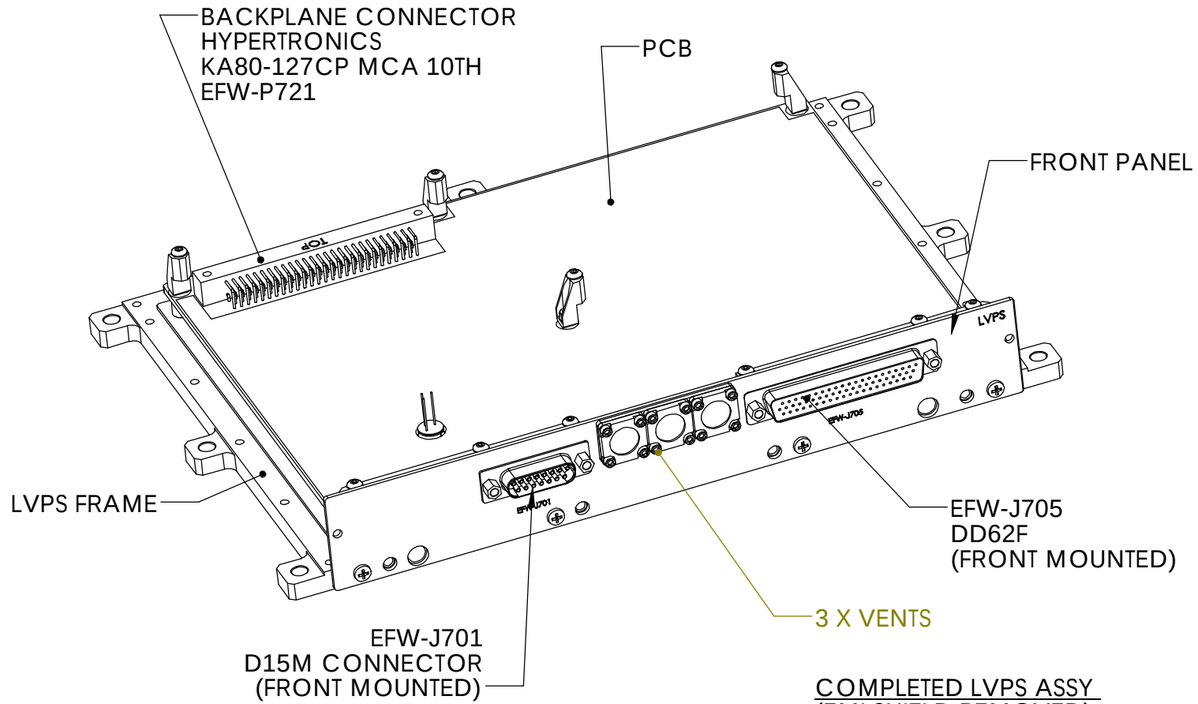
TITLE:
RBSP LVPS
PCB LAYOUT

SIZE	DWG. NO.	REV
B	RBSP-IDP-MEC-002	J
SCALE: -	WEIGHT: LBS	SHEET 1 OF 3

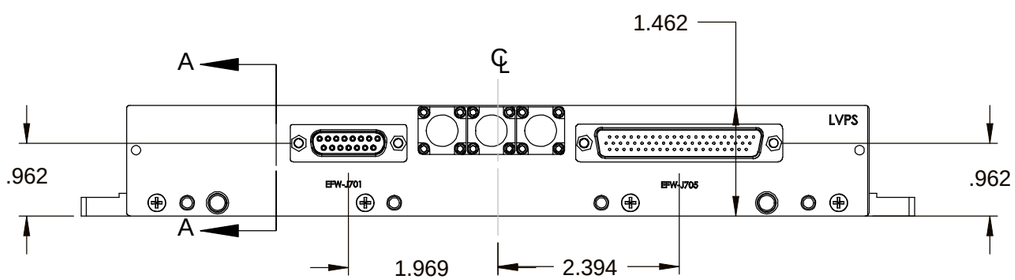
REVISIONS		
REV.	DESCRIPTION	DATE
C	SEE SHEET 1	-
D	CHANGED CONNECTOR TO PANEL MOUNTED; SHORTENED COMPONENT HEIGHT TO .800" (WAS 1.000")	03 DEC 2008
E	INCREASED HEIGHT OF CONNECTORS AND VENTS; SHIFTED PCB UP BY .125"; INCREASED CLEARANCE HT FOR COMPONENTS UNDER PCB	17.APRIL.2009
F	SEE SH 1 (NO CHANGES THIS SH)	01.JUNE.2009
G	SEE SH 1 (NO CHANGES THIS SH)	03.JUNE.2009
H	SEE SH 1 (NO CHANGES THIS SH)	01.JULY.2009
J	SEE SH1 (NO CHANGES THIS SH)	13.APRIL.2010



COMPLETED LVPS ASSY

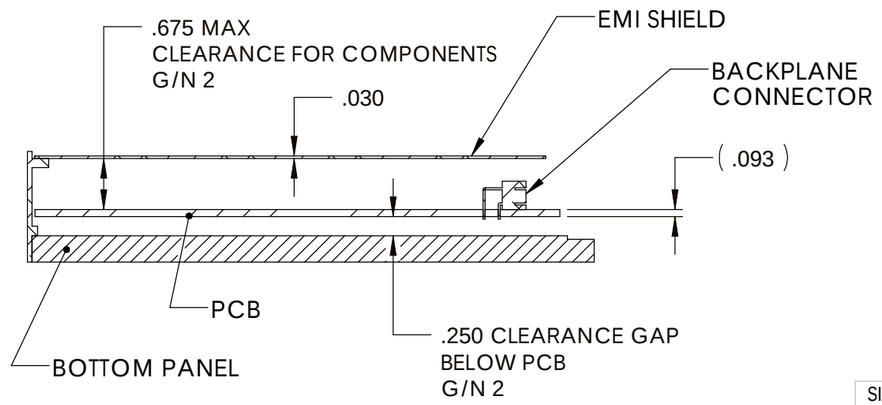


COMPLETED LVPS ASSY
(EMI SHIELD REMOVED)



FRONT PANEL DETAILS

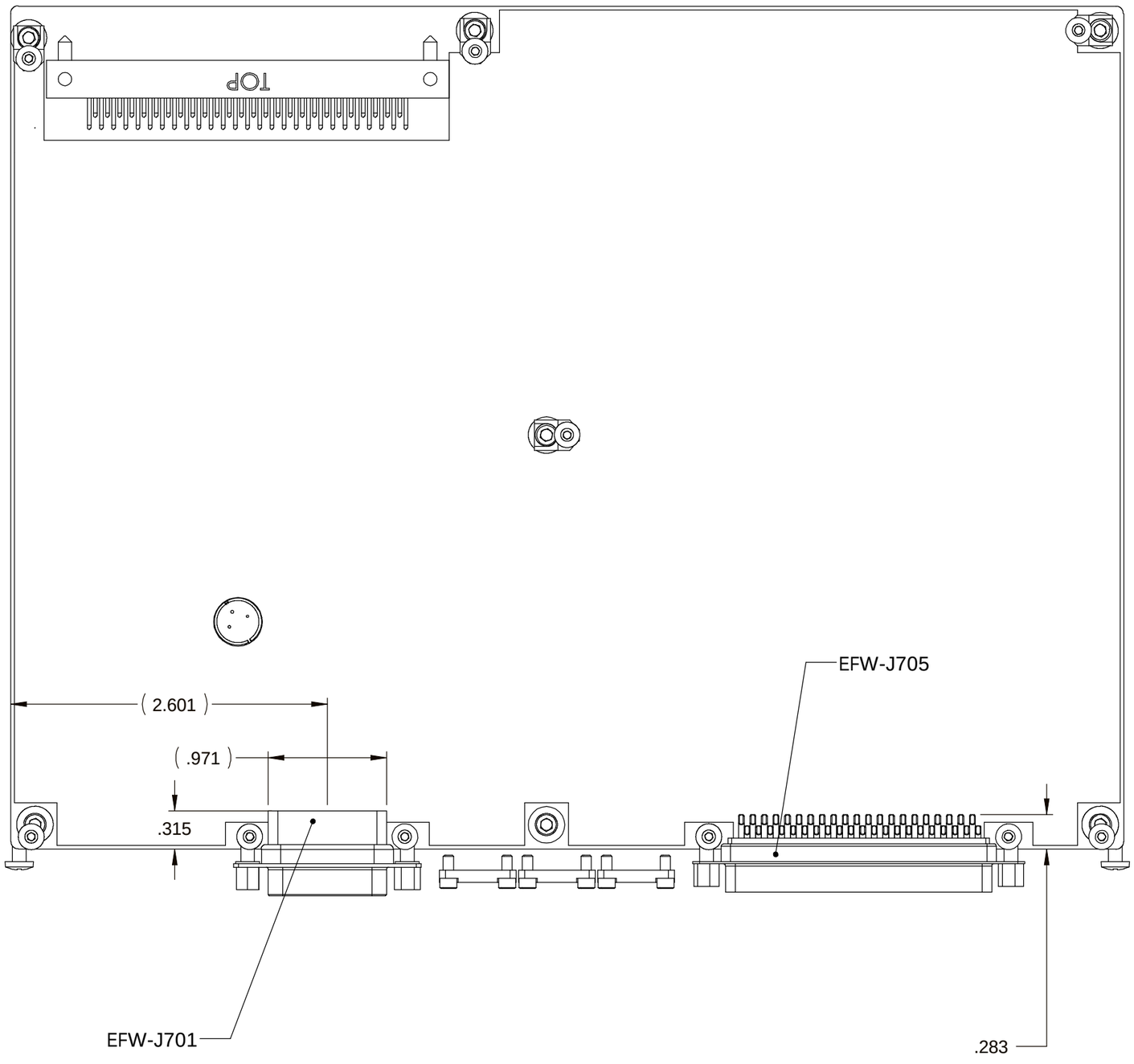
4 SCALE 1/2



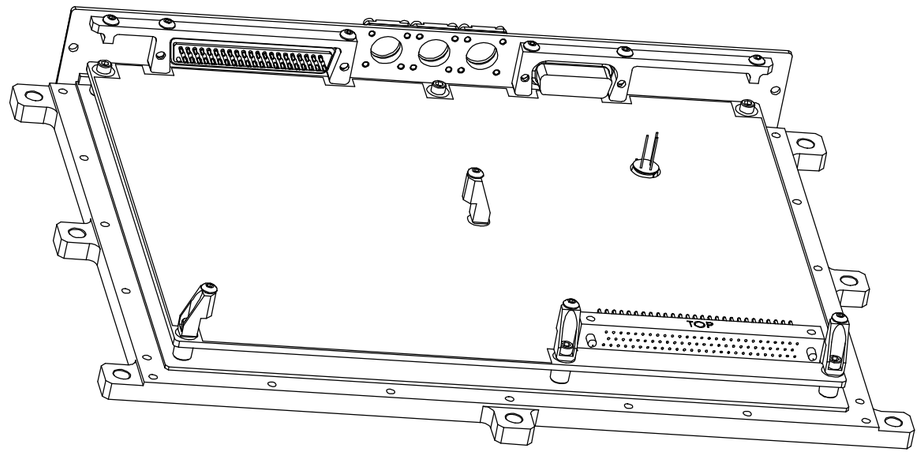
SECTION A-A

SIZE	DWG. NO.	REV
B	RBSP-IDP-MEC-002	J
SCALE: 1:2	WEIGHT:	SHEET 2 OF 3

REVISIONS		
REV.	DESCRIPTION	DATE
G	ADDED SHEET 3	03.JUNE.2009
H	SEE SH 1 (NO CHANGES THIS SHEET)	01.JULY.2009
J	SEE SH1 (NO CHANGES THIS SHEET)	13.APRIL.2010



VIEW LOOKING DOWN AT PCB SHOWING CONNECTOR EXTENSION ON PCB



VIEW SHOWING BACK OF FRONT PANEL

SIZE	DWG. NO.	REV
B	RBSP-IDP-MEC-002	J
SCALE: 1:2		SHEET 3 OF 3